Preferred Device

SWITCHMODE ™ **Power Rectifier**

Ultrafast "E" Series with High Reverse Energy Capability

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- 20 mjoules Avalanche Energy Guaranteed
- Excellent Protection Against Voltage Transients in Switching Inductive Load Circuits
- Ultrafast 75 Nanosecond Recovery Time
- 175°C Operating Junction Temperature
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- These are Pb-Free Devices*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max for 10 Seconds
- Polarity: Cathode Indicated by Polarity Band

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$egin{array}{c} V_{RRM} \ V_{RWM} \ V_{R} \end{array}$	1000	٧
Average Rectified Forward Current (Note 1)	I _{F(AV)}	2.0 @ T _A = 35°C	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I _{FSM}	35	A
Operating Junction Temperature and Storage Temperature Range	T _J , T _{stg}	-65 to +175	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	(Note 3)	°C/W

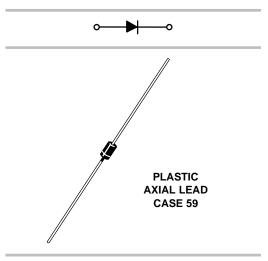
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIER2.0 AMPERES, 1000 VOLTS



MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MUR2100E	Axial Lead**	1000 Units/Bag
MUR2100EG	Axial Lead**	1000 Units/Bag
MUR2100ERL	Axial Lead**	5000/Tape & Reel
MUR2100ERLG	Axial Lead**	5000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

^{1.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

^{**}This package is inherently Pb-Free.

看信TRICAL CHARACTERISTICS

<u> </u>	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{array}{l} (I_F=2.0 \text{ A, T}_J=150^{\circ}\text{C}) \\ (I_F=2.0 \text{ A, T}_J=25^{\circ}\text{C}) \end{array} $	V _F	1.75 2.20	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 100^{\circ}\text{C}$) (Rated dc Voltage, $T_J = 25^{\circ}\text{C}$)	i _R	600 10	μΑ
Maximum Reverse Recovery Time $ \begin{aligned} (I_F = 1.0 \text{ A, di/dt} = 50 \text{ A/}\mu\text{s}) \\ (I_F = 0.5 \text{ A, } I_R = 1.0 \text{ A, } I_{REC} = 0.25 \text{ A}) \end{aligned} $	t _{rr}	100 75	ns
Maximum Forward Recovery Time (I _F = 1.0 A, di/dt = 100 A/ μ s, I _{REC} to 1.0 V)	t _{fr}	75	ns
Controlled Avalanche Energy (See Test Circuit in Figure 6)	W _{AVAL}	10	mJ

^{2.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

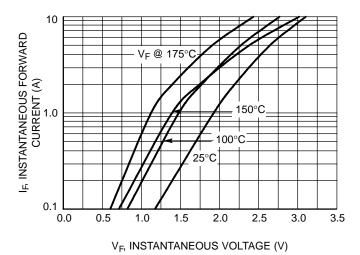


Figure 1. Maximum Forward Voltage

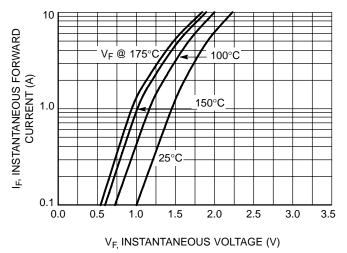
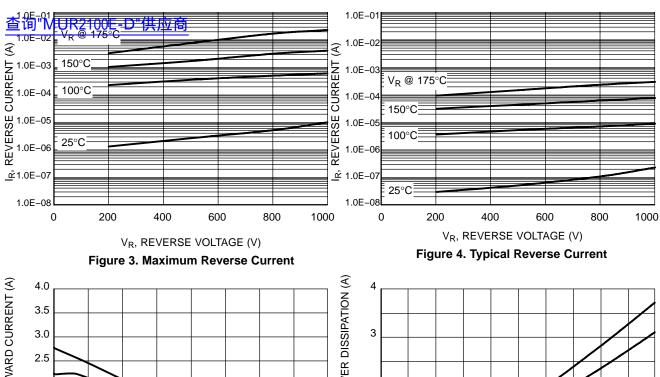


Figure 2. Typical Forward Voltage

MUR2100E



P_{F(AV)}, AVERAGE POWER DISSIPATION (A) I_{F(AV)}, AVERAGE FORWARD CURRENT (A) 2.0 DC SQUARE WAVE DC 1.5 SQUARE WAVE 1.0 0.5 0 0 100 200 0.5 50 0 1.5 2 T_A , AMBIENT TEMPERATURE (°C) I_{F(AV)}, AVERAGE FORWARD CURRENT (A)



Figure 6. Power Dissipation

2.5

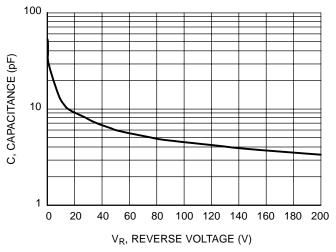


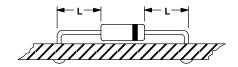
Figure 7. Typical Capacitance

Data shown for thermal resistance, junction—to—ambient $(R_{\theta JA})$ for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

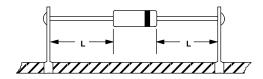
TYPICAL VALUES FOR $R_{\theta \text{JA}}$ IN STILL AIR

Mounti	ng	Lead Length, L			
Method		1/8	1/4	1/2	Units
1		52	65	72	°C/W
2	$R_{\theta JA}$	67	80	87	°C/W
3			50		°C/W

MOUNTING METHOD 1

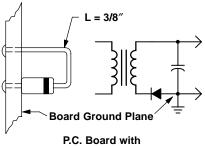


MOUNTING METHOD 2



Vector Pin Mounting

MOUNTING METHOD 3



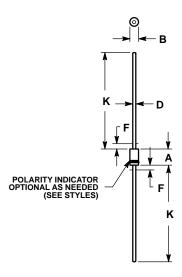
1–1/2" X 1–1/2" Copper Surface

MUR2100E

查询"MUR2100E-D"供应商

PACKAGE DIMENSIONS

AXIAL LEAD CASE 59-10 ISSUE U



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- ALL RULES AND NOTES ASSOCIATED WITH JEDEC DO-41 OUTLINE SHALL APPLY POLARITY DENOTED BY CATHODE BAND. LEAD DIAMETER NOT CONTROLLED WITHIN F

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.161	0.205	4.10	5.20
В	0.079	0.106	2.00	2.70
D	0.028	0.034	0.71	0.86
F		0.050		1.27
ĸ	1.000		25.40	

STYLE 1: PIN 1. CATHODE (POLARITY BAND)

2. ANODE

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